

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re the Application of: **Koji NOZAKI et al.**

Group Art Unit: **1795**

Application Number: **10/623,679**

Examiner: **Amanda C. Walke**

Filed: **July 22, 2003**

Confirmation Number: **5083**

For: **RESIST PATTERN THICKENING MATERIAL, RESIST  
PATTERN AND PROCESS FOR FORMING THE SAME, AND  
SEMICONDUCTOR DEVICE AND PROCESS FOR  
MANUFACTURING THE SAME**

Attorney Docket Number: **030891**

Customer Number: **38834**

**AMENDMENT UNDER 37 C.F.R. § 1.116**  
**EXPEDITED PROCESSING REQUESTED**

DO NOT ENTER: /ACW/

11/03/2008

**MAILSTOP: AF**

Commissioner for Patents

P. O. Box 1450

Alexandria, VA 22313-1450

October 30, 2008

Sir:

This paper is filed in response to the Office Action dated May 30, 2008, the response due date extended to October 30, 2008 by a two-months Extension of Time.

**Amendments to the Claims** begin on page 2 of this paper.

**Remarks** begin on page 12 of this paper.